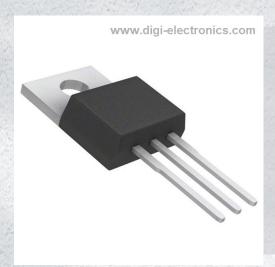


FCP190N65F Datasheet



https://www.DiGi-Electronics.com

DiGi Electronics Part Number FCP190N65F-DG

Manufacturer onsemi

Manufacturer Product Number FCP190N65F

Description MOSFET N-CH 650V 20.6A TO220-3

Detailed Description N-Channel 650 V 20.6A (Tc) 208W (Tc) Through Hol

e TO-220-3



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Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
FCP190N65F	onsemi
Series:	Product Status:
FRFET®, SuperFET® II	Not For New Designs
FET Type:	Technology:
N-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
650 V	20.6A (Tc)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ ld, Vgs:
10V	190mOhm @ 10A, 10V
Vgs(th) (Max) @ ld:	Gate Charge (Qg) (Max) @ Vgs:
5V @ 2mA	78 nC @ 10 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±20V	3225 pF @ 25 V
FET Feature:	Power Dissipation (Max):
	208W (Tc)
Operating Temperature:	Mounting Type:
-55°C ~ 150°C (TJ)	Through Hole
Supplier Device Package:	Package / Case:
TO-220-3	TO-220-3
Base Product Number:	
ECD100	

Environmental & Export classification

8541.29.0095

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	Not Applicable
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	



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December 2014

FCP190N65F

N-Channel SuperFET[®] II FRFET[®] MOSFET 650 V, 20.6 A, 190 m Ω

Features

- 700 V @ T_J = 150°C
- Typ. $R_{DS(on)}$ = 168 m Ω
- Ultra Low Gate Charge (Typ. Q_q = 60 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 304 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

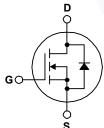
Applications

- · LCD / LED / PDP TV
- Solar Inverter
- · AC DC Power Supply

Description

SuperFET® II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SuperFET II FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter		FCP190N65F	Unit
V _{DSS}	Drain to Source Voltage			650	V
V	Cata ta Cauraa Valtaga	- DC		±20	V
V_{GSS}	Gate to Source Voltage	- AC	(f > 1 Hz)	±30	_ v
	Drain Current	- Continuous (T _C = 25°C)		20.6	Α
'D	Drain Current	- Continuous (T _C = 100°C)		13.1	_ A
I _{DM}	Drain Current	- Pulsed	61.8	Α	
E _{AS}	Single Pulsed Avalanche Energy	Single Pulsed Avalanche Energy (Note 2)			mJ
I _{AR}	Avalanche Current	Avalanche Current			Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	2.1	mJ
dv/dt	MOSFET dv/dt			100	V/ns
uv/ut	Peak Diode Recovery dv/dt	50	V/115		
D	Dawer Dissipation	(T _C = 25°C)		208	W
P_{D}	Power Dissipation	- Derate Above 25°C		1.67	W/°C
T _J , T _{STG}	Operating and Storage Tempera	ture Range		-55 to +150	°C
T _L	Maximum Lead Temperature for 1/8" from Case for 5 Seconds	Soldering,		300	°C

Thermal Characteristics

Symbol	Parameter	FCP190N65F	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.6	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	C/W

Package Marking and Ordering Information

	Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
Ī	FCP190N65F	FCP190N65F	TO-220	Tube	N/A	N/A	50 units

Test Conditions

Min.

Тур.

Max.

Unit

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted. Parameter

Off Charact	eristics					
D)/	Drain to Course Prockdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 25^{\circ}\text{C}$	650	-	-	W
BV _{DSS} Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 150 ^{\circ}\text{C}$	700	-	-	V	
$\Delta BV_{DSS} / \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C	-	0.72	-	V/°C
1	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	-	-	10	
DSS	Zero Gale Vollage Drain Current	$V_{DS} = 520 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	60	-	μА
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

Symbol

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 2 \text{ mA}$	3	-	5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	-	168	190	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 20 V, I _D = 10 A	-	18	1	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V - 25 V V - 0 V	_	2425	3225	pF
C _{oss}	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	-	2110	2805	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12	-	105	155	pF
C _{oss}	Output Capacitance	$V_{DS} = 380 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	44	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	304	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 380 V, I _D = 10 A,	-	60	78	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	12	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	25	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.6	-	Ω

Switching Characteristics

	T 0 D 1 T						
t _{d(on)}	Turn-On Delay Time			-	25	60	ns
t _r	Turn-On Rise Time	$V_{DD} = 380 \text{ V}, I_{D} = 10 \text{ A},$		-/	11	32	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_g = 4.7 Ω		-	62	134	ns
t _f	Turn-Off Fall Time		(Note 4)	-	4.2	18	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	20.6	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	61.8	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 10 A	-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 10 A,	-	105	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	515	-	nC

- 1. Repetitive rating: pulse width limited by maximum junction temperature.
- 2. I_{AS} = 4 A, R_G = 25 Ω , starting T_J = 25°C.
- 3. $I_{SD} \leq$ 10 A, di/dt \leq 200 A/µs, $V_{DD} \leq$ 380 V, starting T_J = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

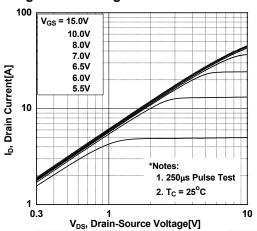


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

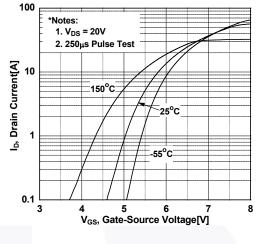


Figure 2. Transfer Characteristics

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

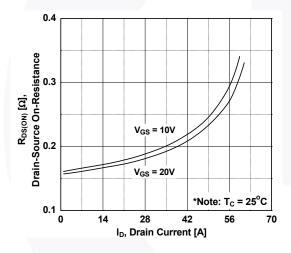
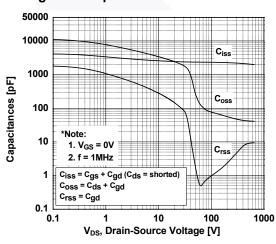
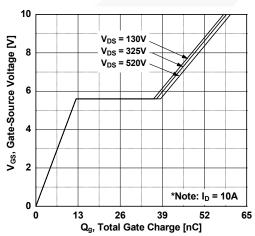


Figure 5. Capacitance Characteristics



100 10 Reverse Drain Current [A] 150°C 25°C 0.1 0.01 *Notes: 1. V_{GS} = 0V 2. 250μs Pulse Test 0.001 0.0 0.3 0.6 0.9 V_{SD}, Body Diode Forward Voltage [V]

Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

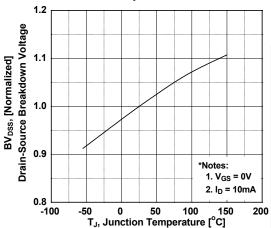


Figure 9. Maximum Safe Operating Area

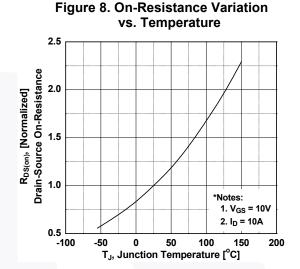


Figure 10. Maximum Drain Current vs. Case Temperature

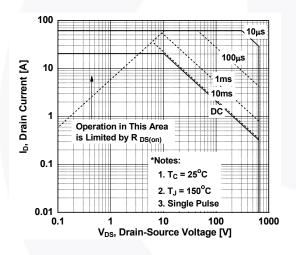
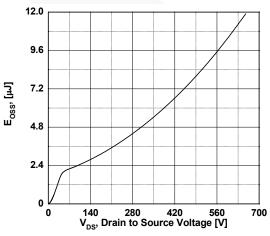
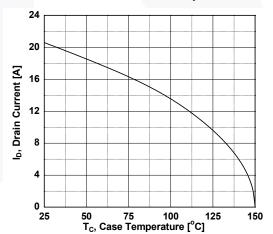


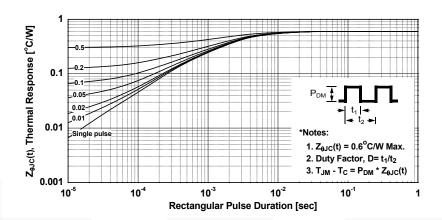
Figure 11. Eoss vs. Drain to Source Voltage





Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



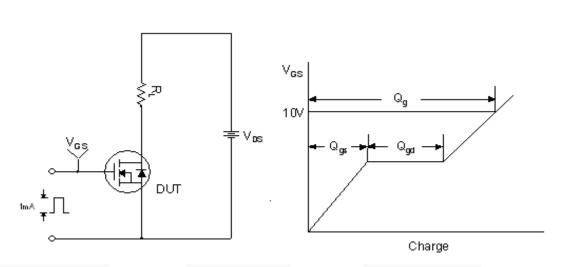


Figure 13. Gate Charge Test Circuit & Waveform

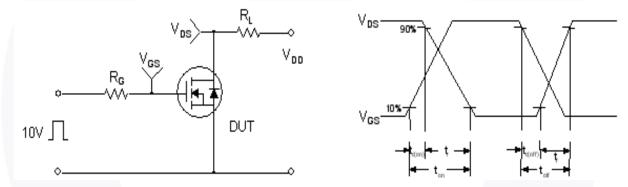


Figure 14. Resistive Switching Test Circuit & Waveforms

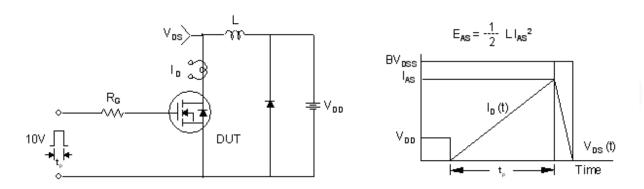


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

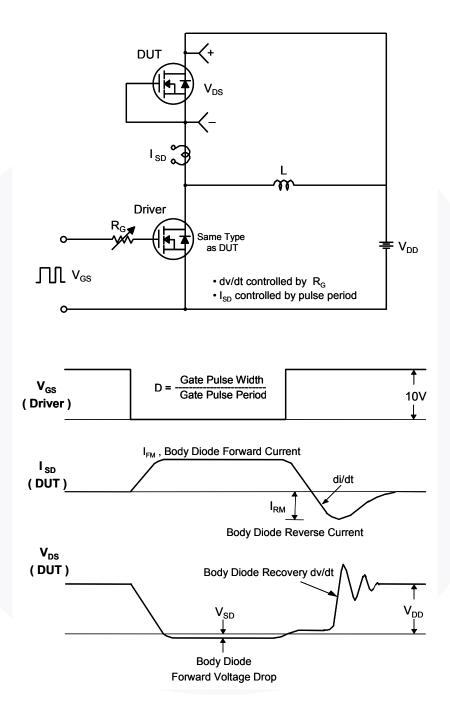
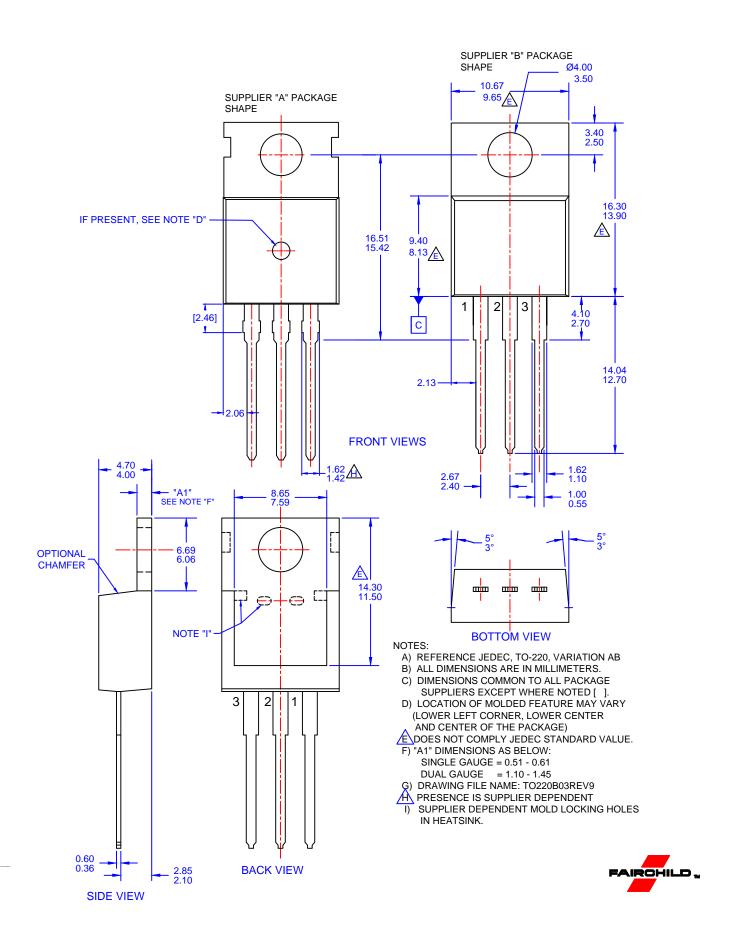


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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